

FEATURES

- Low $V_{CE(sat)}$ Device
- 10.2kV Isolation
- 10 μ s Short Circuit Withstand
- High Thermal Cycling Capability
- High Current Density Enhanced DMOS SPT
- Isolated AISiC Base With AlN Substrates

APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 1200V to 6500V and currents up to 2400A.

The DIM1500ASM33-TL001 is a Low $V_{CE(sat)}$ single switch 3300V, n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10 μ s short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM1500ASM33-TL001

Note: When ordering, please use the complete part number

KEY PARAMETERS

V_{CES}	3300V
$V_{CE(sat)}$ * (typ)	2.0V
I_C (max)	1500A
$I_{C(PK)}$ (max)	3000A

* Measured at the auxiliary terminals

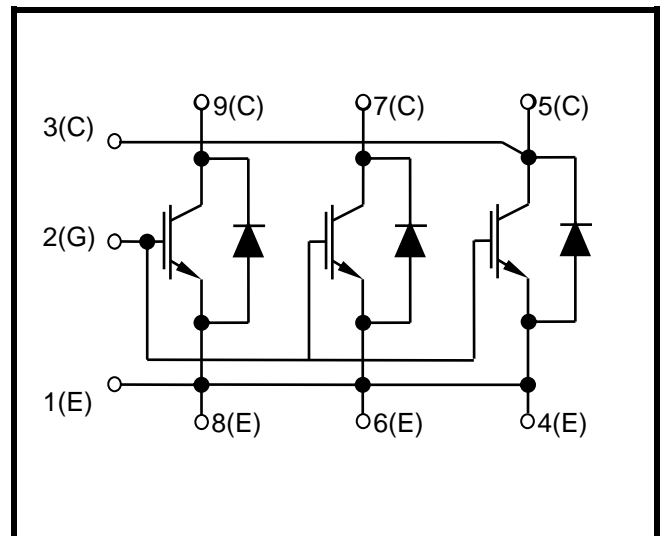


Fig. 1 Circuit configuration



Outline type code: A

(See Fig. 11 for further information)

Fig. 2 Package

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under ‘Absolute Maximum Ratings’ may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
V _{CES}	Collector-emitter voltage	V _{GE} = 0V	3300	V
V _{GES}	Gate-emitter voltage		±20	V
I _C	Continuous collector current	T _{case} = 115°C	1500	A
I _{C(PK)}	Peak collector current	1ms, T _{case} = 140°C	3000	A
P _{max}	Max. transistor power dissipation	T _{case} = 25°C, T _j = 150°C	15.6	kW
I ² t	Diode I ² t value	V _R = 0, t _p = 10ms, T _j = 150°C	720	kA ² s
V _{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	10.2	kV
Q _{PD}	Partial discharge – per module	IEC1287, V ₁ = 6900V, V ₂ = 5100V, 50Hz RMS	10	pC

THERMAL AND MECHANICAL RATINGS

Internal insulation material: AIN
 Baseplate material: AISiC
 Creepage distance: 56mm
 Clearance: 26mm
 CTI (Comparative Tracking Index): >600

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
R _{th(j-c)}	Thermal resistance – transistor	Continuous dissipation - junction to case	-	-	8	°C/kW
R _{th(j-c)}	Thermal resistance – diode	Continuous dissipation - junction to case	-	-	16	°C/kW
R _{th(c-h)}	Thermal resistance – case to heatsink (per module)	Mounting torque 5Nm (with mounting grease)	-	-	6	°C/kW
T _j	Junction temperature	Transistor	-	-	150	°C
		Diode	-	-	150	°C
T _{stg}	Storage temperature range	-	-40	-	125	°C
	Screw torque	Mounting – M6	-	-	5	Nm
		Electrical connections – M4	-	-	2	Nm
		Electrical connections – M8	-	-	10	Nm

ELECTRICAL CHARACTERISTICS

$T_{case} = 25^{\circ}C$ unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
I_{CES}	Collector cut-off current	$V_{GE} = 0V, V_{CE} = V_{CES}$			5	mA
		$V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 125^{\circ}C$			90	mA
		$V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 150^{\circ}C$			150	mA
I_{GES}	Gate leakage current	$V_{GE} = \pm 20V, V_{CE} = 0V$			1	μA
$V_{GE(TH)}$	Gate threshold voltage	$I_C = 120mA, V_{GE} = V_{CE}$		5.7		V
$V_{CE(sat)}^{\dagger}$	Collector-emitter saturation voltage	$V_{GE} = 15V, I_C = 1500A$		2.0	2.2	V
		$V_{GE} = 15V, I_C = 1500A, T_j = 125^{\circ}C$		2.6		V
		$V_{GE} = 15V, I_C = 1500A, T_j = 150^{\circ}C$		2.8	3.2	V
I_F	Diode forward current	DC		1500		A
I_{FM}	Diode maximum forward current	$t_p = 1ms$		3000		A
V_F^{\dagger}	Diode forward voltage	$I_F = 1500A$		2.4		V
		$I_F = 1500A, T_j = 125^{\circ}C$		2.5		V
		$I_F = 1500A, T_j = 150^{\circ}C$		2.4		V
C_{ies}	Input capacitance	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$		260		nF
Q_g	Gate charge	$\pm 15V$ Including external C_{ge}		25		μC
C_{res}	Reverse transfer capacitance	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$		6		nF
L_M	Module inductance			10		nH
R_{INT}	Internal transistor resistance			90		$\mu\Omega$
SC_{Data}	Short circuit current, I_{SC}	$T_j = 150^{\circ}C, V_{CC} = 2500V$ $t_p \leq 10\mu s, V_{GE} \leq 15V$ $V_{CE(max)} = V_{CES} - L^* \times dl/dt$ IEC 60747-9		5500		A

Note:

\dagger Measured at the auxiliary terminals

* L is the circuit inductance + L_M

ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1500A V _{GE} = ±15V V _{CE} = 1800V R _{g(ON)} = 1.65Ω R _{g(OFF)} = 1.5Ω C _{GE} = 330nF L _S ~ 150nH		2700		ns
t _f	Fall time			610		ns
E _{OFF}	Turn-off energy loss			3750		mJ
t _{d(on)}	Turn-on delay time			960		ns
t _r	Rise time			430		ns
E _{ON}	Turn-on energy loss			2400		mJ
Q _{rr}	Diode reverse recovery charge	I _F = 1500A V _{CE} = 1800V dI _F /dt = 4000A/μs		850		μC
I _{rr}	Diode reverse recovery current			920		A
E _{rec}	Diode reverse recovery energy			1000		mJ

T_{case} = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1500A V _{GE} = ±15V V _{CE} = 1800V R _{g(ON)} = 1.65Ω R _{g(OFF)} = 1.5Ω C _{GE} = 330nF L _S ~ 150nH		2750		ns
t _f	Fall time			590		ns
E _{OFF}	Turn-off energy loss			4050		mJ
t _{d(on)}	Turn-on delay time			1000		ns
t _r	Rise time			460		ns
E _{ON}	Turn-on energy loss			3100		mJ
Q _{rr}	Diode reverse recovery charge	I _F = 1500A V _{CE} = 1800V dI _F /dt = 4000A/μs		1400		μC
I _{rr}	Diode reverse recovery current			1160		A
E _{rec}	Diode reverse recovery energy			1700		mJ

T_{case} = 150°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Typ.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 1500A V _{GE} = ±15V V _{CE} = 1800V R _{g(ON)} = 1.65Ω R _{g(OFF)} = 1.5Ω C _{GE} = 330nF L _S ~ 150nH		2760		ns
t _f	Fall time			590		ns
E _{OFF}	Turn-off energy loss			4400		mJ
t _{d(on)}	Turn-on delay time			940		ns
t _r	Rise time			460		ns
E _{ON}	Turn-on energy loss			3400		mJ
Q _{rr}	Diode reverse recovery charge	I _F = 1500A V _{CE} = 1800V dI _F /dt = 4000A/μs		1600		μC
I _{rr}	Diode reverse recovery current			1200		A
E _{rec}	Diode reverse recovery energy			1950		mJ

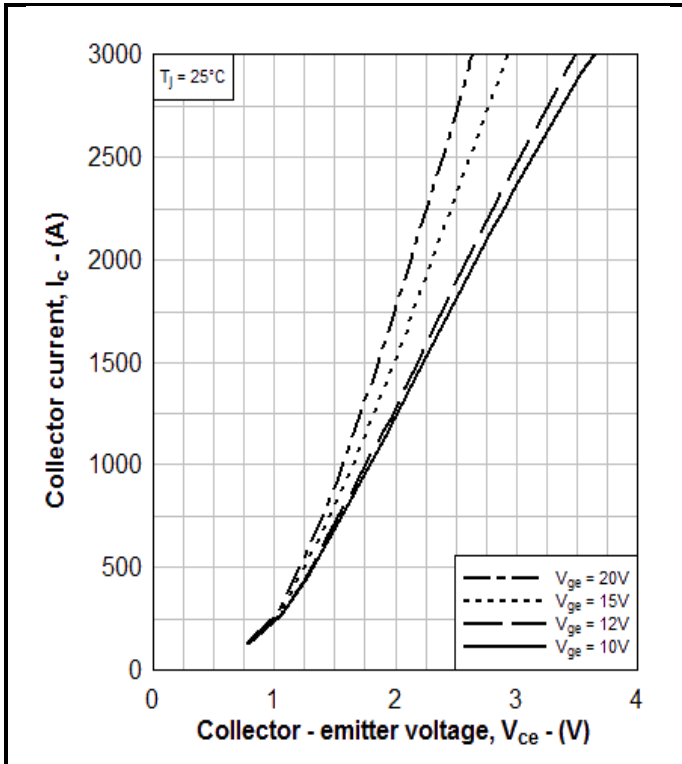


Fig. 3 Typical output characteristics

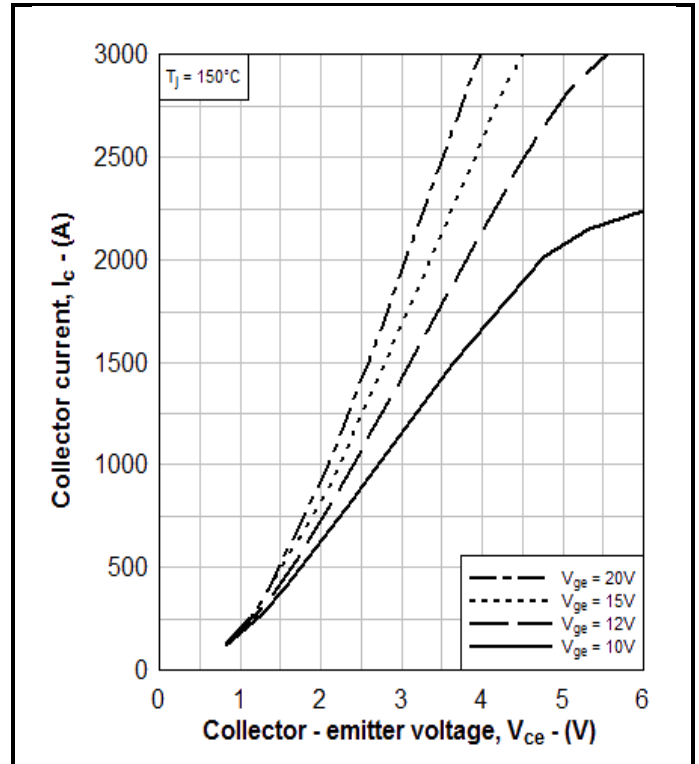


Fig. 4 Typical output characteristics

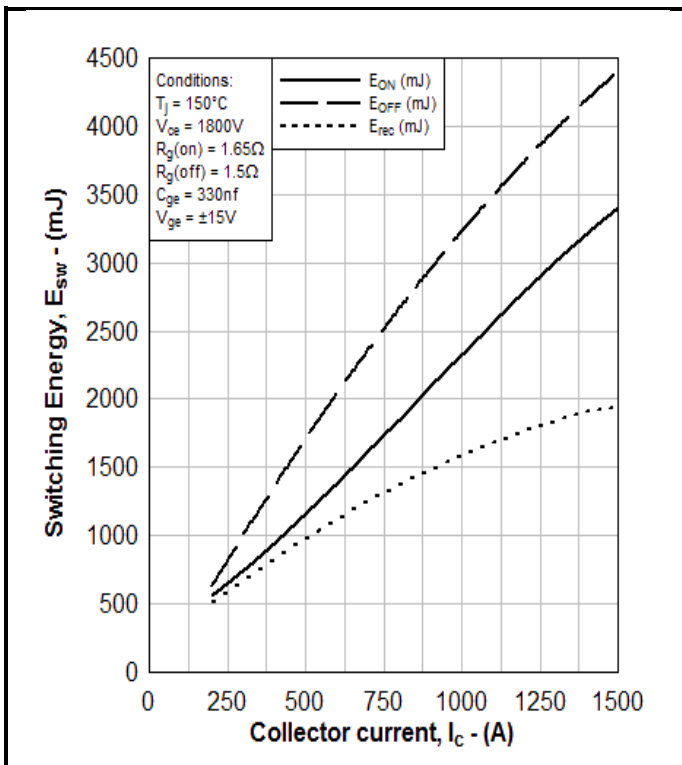


Fig. 5 Typical switching energy vs collector current

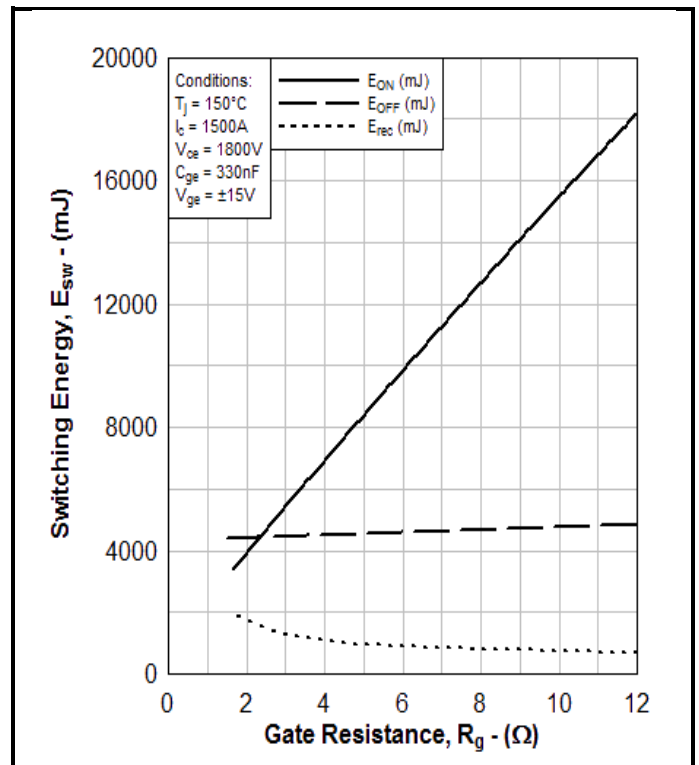


Fig. 6 Typical switching energy vs gate resistance

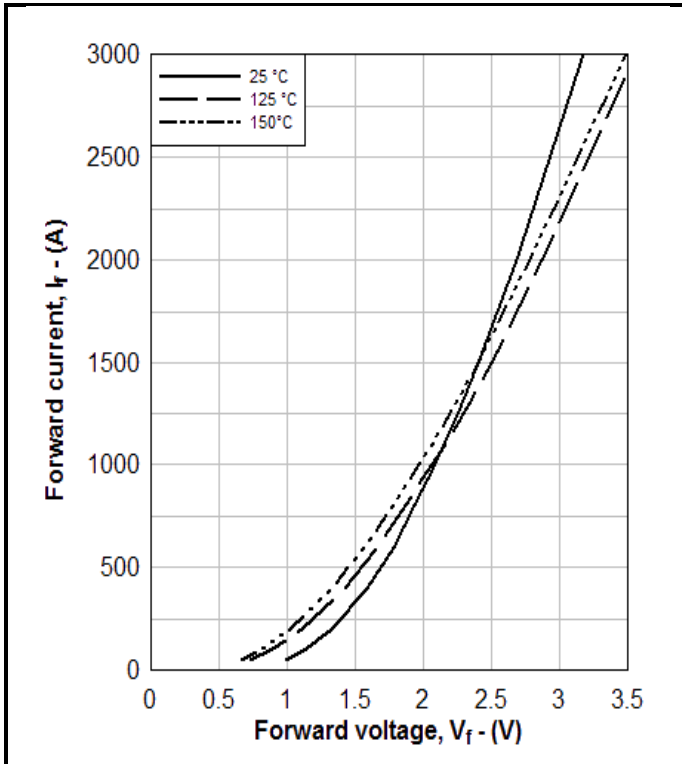


Fig. 7 Diode typical forward characteristics

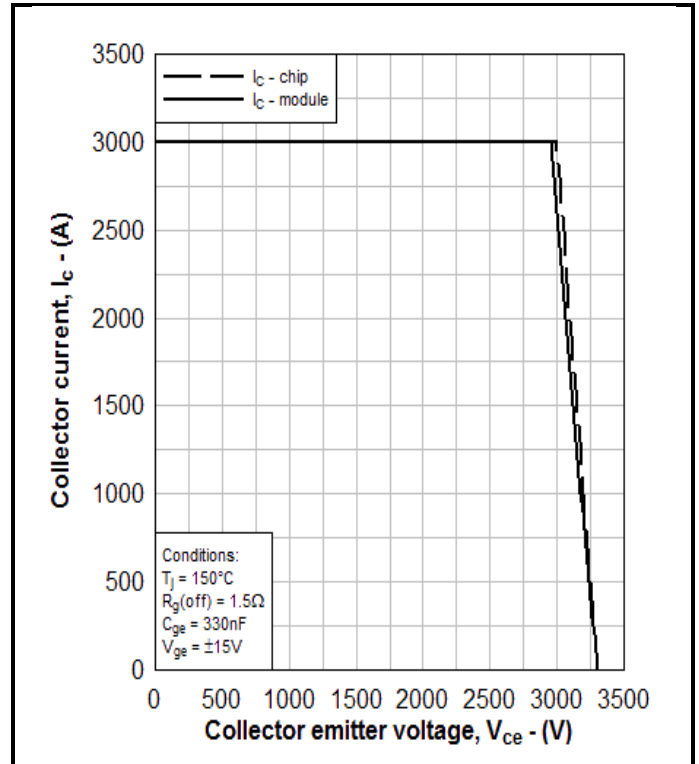


Fig. 8 Reverse bias safe operating area

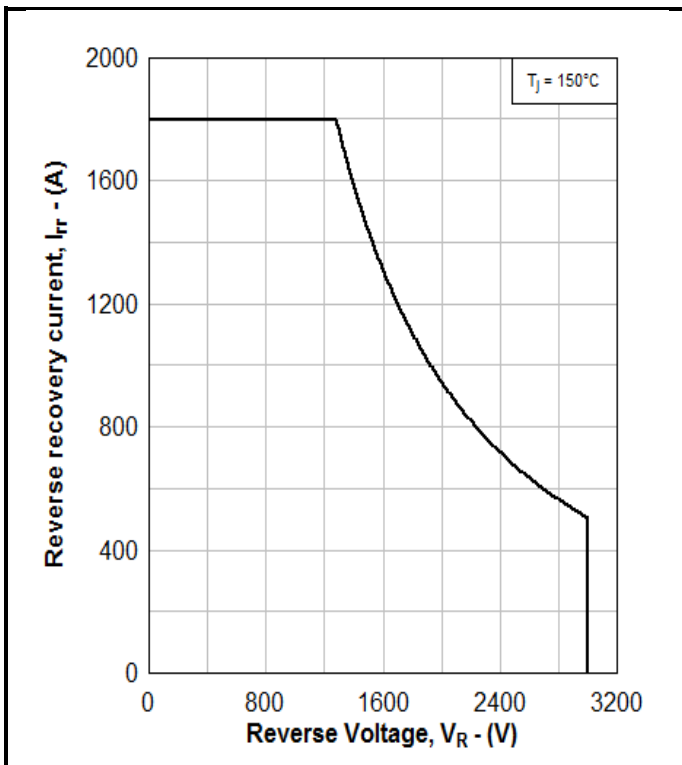


Fig. 9 Diode reverse bias safe operating area

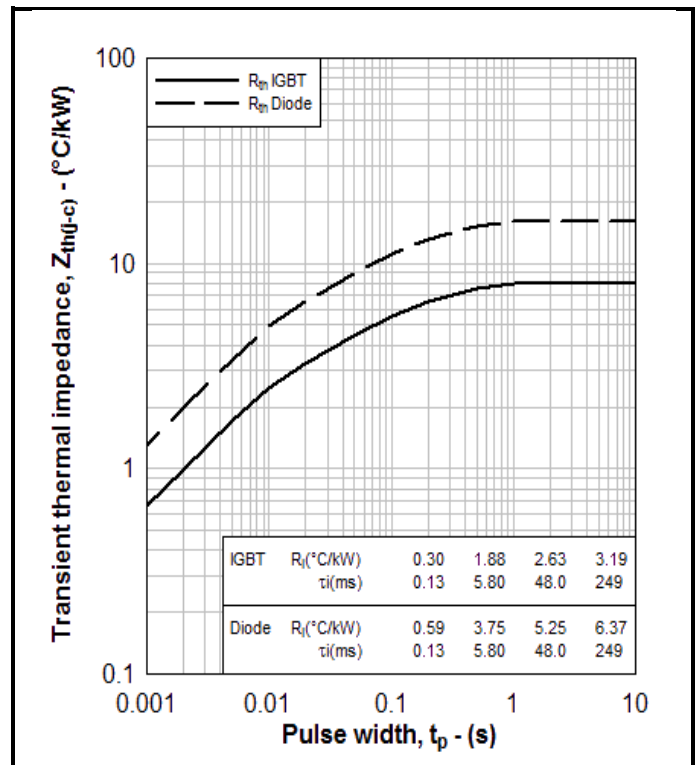


Fig. 10 Transient thermal impedance

PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services.
All dimensions in mm, unless stated otherwise.
DO NOT SCALE.

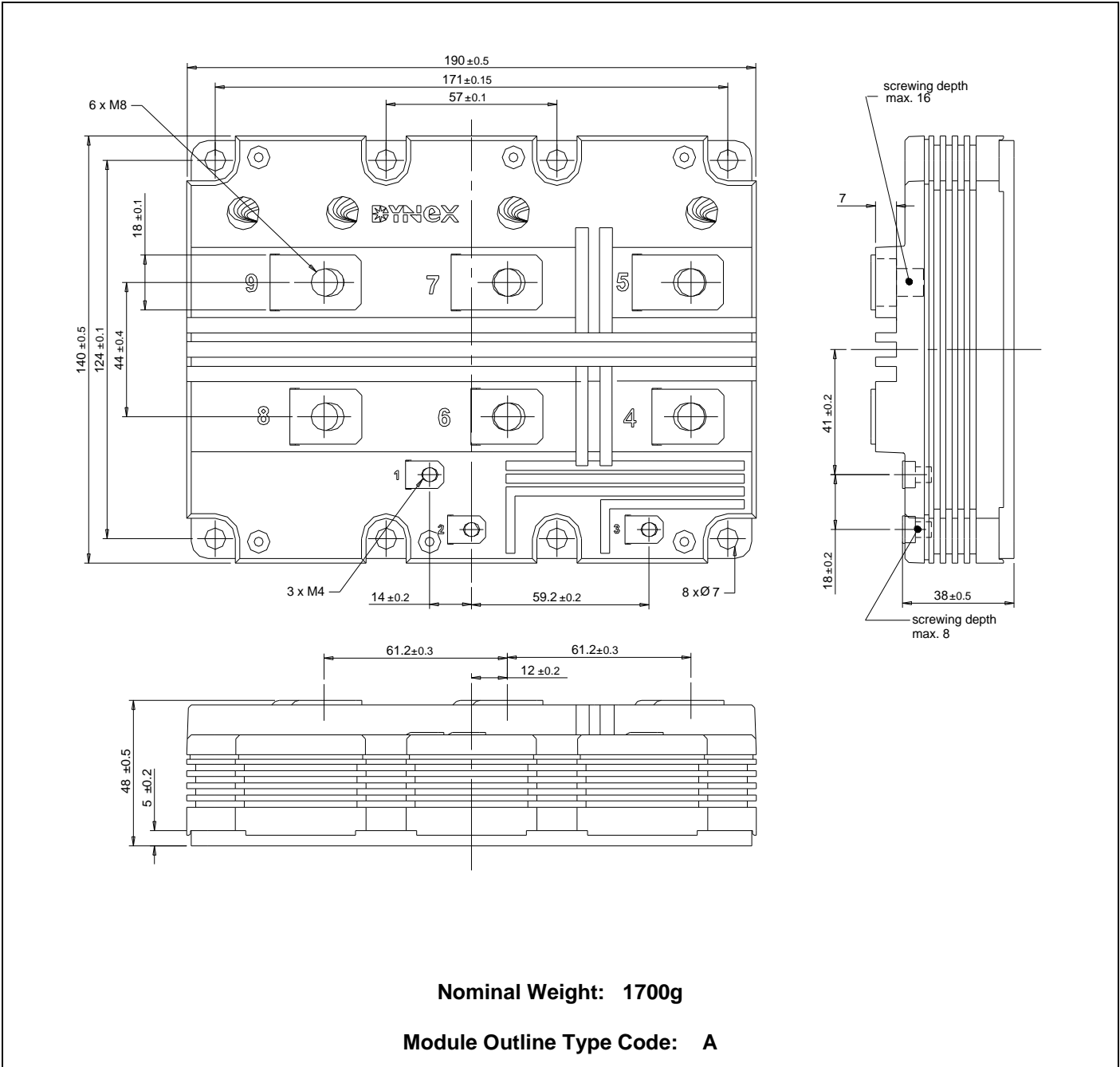


Fig. 11 Module outline drawing

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